Amphenol® High Density HDB³ and HSB³ Connector Series

SL-402







HSB³ High Speed









TABLE OF CONTENTS Page No.

Performance/Features	1
HDB ³ Mother Board	2
HDB ³ Daughter Board	3
HDB ³ I/O Connector	4
HDB ³ Stacker Connector	5
HSB ³ High Speed Mother Board	6
HSB ³ High Speed Daughter Board	7
HSB ³ High Speed Layout	8
HSB ³ High Speed Recommended Board Layout	9
Hardware for HDB ³ and HSB ³	10
Other Amphenol Rectangular Products	11
Notes	12
Sales Office and Distributor Listing	12



BRISTLE BRUSH ADVANTAGES

The superior choice for board level interconnects

The Bristle Brush contact has been proven in military avionics packages and meets the requirements of MIL-DTL-55302. It provides high density in tighter spacing which is a main concern for integrated electronics in aircraft systems.

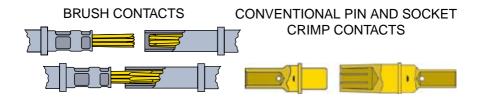
Brush vs. Conventional Contacts

Brush Contact Innovation

- Multiple contact interfaces: Strands of high tensile strength wire are bundled together to form brush-like contacts. By intermeshing two multi-strand wire bundles, an electrical connection is made.
- Provides redundant current paths, 14-70 (point of contact) per mated contact with a gas tight junction.
- · Very smooth (low friction) interface

Conventional Pin/Socket

- Machined surface finish on both parts
- · Higher friction and wear
- · Limited number of contact sites



Amphenol Brush Contact Provides:

- Low mating forces (70% to 90% lower than conventional pin and socket contacts
- Easy mating/unmating makes high circuit counts practical (25 lbs. typical for 400 contacts)
- Multiple points of contact = superior electrical capability
 - Stable, low resistance-20milliohms max.
 - · Redundant current paths
 - · Proven electrical and gas tight contact sites
- · Severe environment protection
- High current rating
- Long contact life (100,000 cycles of mating and unmating with out performance degradation)
- Documented intermittency-free performance no 10 nanosecond discontinuities during 50,000,000 cycles of 0.010 displacement
- · Overall cost effectiveness (life cycle cost)
- · Protection against micro-arcing
- · No degradation in a fretting/micro-motion environment

HIGH DENSITY BRUSH (HDB3) SERIES

HDB³ High Density Brush Series with tighter (.070 inch X .060 inch) staggered grid spacing

This new connector series of brush connectors incorporates a higher density contact pattern and lower mated height than Amphenol's standard low mating force rectangular connectors. HDB³ connectors utilize the same durable and reliable B³ brush contact in a tighter .070" X .060" staggered grid pattern. They offer the advantage of higher density in a compact-height connector utilizing less board space. Styles include mother board, daughter board, input/output and stacker.



HDB³ MATERIALS

Insulator: Liquid crystal polymer, 30% glass filled

Wire: Beryllium copper per ASTM B197; finish is gold per

ASTM B488 over nickel per AMS-QQ-N-290.

Holder: Brass similar to UNS C33500; available finishes

include gold per MIL-G-45204, tin-lead per

MIL-P-81728 or tin per MIL-T-10727 (RoHS Compliant).

Sleeve: Stainless Steel per AMS-5514, passivated IAW

QQ-P-35 (Daughter Board, I/O and Stacker connector)

Keys/Guide Pins: Stainless Steel

Contact:

COMPARISON

COMPARISON

The Amphenol HDB³ Connector offers advantages over competitive connectors:

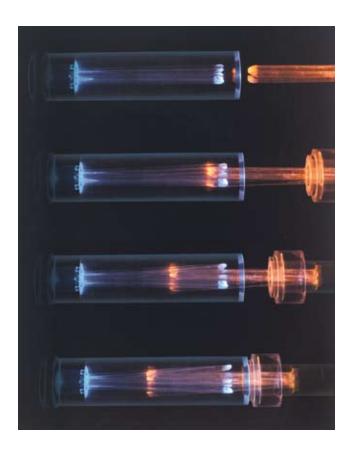
- Higher density contact pattern
- Uses less board space
- · Allows for shorter mated height
- Provides the durability and performance of the Brush contact
- Low cost

	Amphenol HDB ³	Hypertronics HPH	Airborn RM4
Contact System	Brush	Hyperboloid	Pin & Socket
Durability, Mating Cycles	100,000	2,000	500
Contact Mating Forces, Ounces	1.5	1.5	2.5
Mother Board	.070 X .060	.075 X .075	.075 X .070
Daughter Board	.070 X .060	.075 X .100	.075 X .100
Connector Width	.350	.443	.400
Mated Height, MB to 4th row of DB	.680	.986	.915



HDB³ AND HSB³ FEATURES AND BENEFITS

PERFORMANCE



FEATURES

FEATURES

Polarization: "D" shaped design

Keying: Optional keys offer 36 unique

keying combinations

Guide Pins Optional guide pins provide

additional alignment

Radial Misalignment: Capable of correcting up to a

.020" initial radial misalignment

Angular Misalignment: Capable of mating with up to a

2° initial angular misalignment

CONNECTOR PERFORMANCE

Durability: 100,000 mating cycles

Insertion/Extraction Force: 1.5 ounce typical per contact

Operating Temperature: -65° to 125°C

Current Rating: 2 amperes Hot swap 1 ampere

maximum (load dependent)

Insulation Resistance: 5 gigaohms minimum Dielectric Withstanding

Voltage: 750 volts, 60 hertz, rms @ Sea

Level 250 volts, 60 hertz, rms @ 70,000 feet Elevation

Solderability: MIL-STD-202, Method 208

Salt Fog: 48 Hours IAW MIL-STD-1344,

method 1001, test condition B

Humidity: IAW MIL-STD-1344, method

1002, type II

Vibration: 4 hours in each of 3 mutually

perpendicular axes IAW MIL-ST

1344, method 2005, test condition V, letter H

Shock: 1 shock along each of three

mutually perpendicular axes IAW MIL-STD-1344, method

2004,test condition G

Data Rate (HSB³): Capable of 3.125 Gbps (consult

Amphenol for arrangement)

HDB3 & HSB3



HDB³ MOTHER BOARD

HDB³ MOTHER BOARD – HOW TO ORDER

HDB-M4

Mates with:
• Daughter Board 1. 2. 3. 4. 5. 6. Number of Brush Wire Contact Termination Less Hardware Termination I/O Stacker (Purchased separately see Contacts **Plating** Finish pg 10 for hardware options)

040

1. Connector Type

HDB-M4

Designates HDB3 Mother Board

2. Number of Contacts

	Number of	Dimension A	Dimension C
	Contacts		
040	40	1.375	1.075
060	60	1.725	1.425
080	80	2.075	1.775
120	120	1.775	2.475
160	160	3.475	3.175

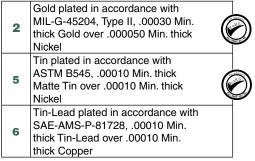
3. Brush Wire Plating

	0.000050 Au Min. thick over Nickel
C	0.000020 Au Min. thick over Nickel

4. Termination

	Туре	Stickout (Dim. E)
22	PCB, Straight, .016 Dia	0.120
23	PCB, Straight, .016 Dia	0.150
24	PCB, Straight, .016 Dia	0.180
26	PCB, Straight, .016 Dia	0.240
28	PCB, Straight, .016 Dia	0.300

5. Contact Termination Finish

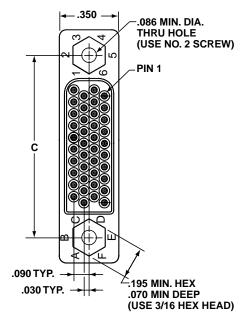


	±.005 +
E ±.020 TYP.	
.016 ±.001 TYP.	

М

24

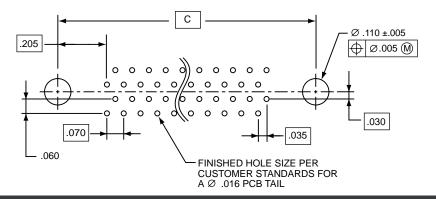
2



X

Connector Dimensions				
No. of Contact Pattern		А	С	
40	4 Row X 10	1.375	1.075	
60	4 Row X 15	1.725	1.425	
80	4 Row X 20	2.075	1.775	
120	4 Row X 30	2.775	2.475	
160	4 Row X 40	3.475	3.175	

MOTHER BOARD LAYOUT



HDB³ DAUGHTER BOARD

HDB3 DAUGHTER BOARD - HOW TO ORDER

Mates with: 5. Mother Board Brush Wire Number of Termination Contact Termination Less Hardware (Purchased separately see Contacts **Plating** Finish pg 10 for hardware options) HDB-D4 040 М 01 2 X

1. Connector Type HDB-D4

Designates HDB3 Daughter Board

2. Number of Contacts

	Number of	Dimension	Dimension
	Contacts	Α	С
040	40	1.375	1.075
060	60	1.725	1.425
080	80	2.075	1.775
120	120	1.775	2.475
160	160	3.475	3.175

3. Brush Wire Plating

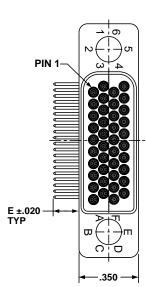
	0.000050 Au Min. thick over Nickel
C	0.000020 Au Min. thick over Nickel

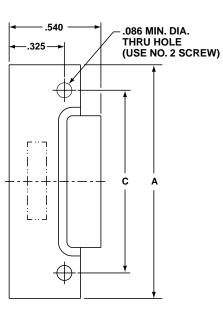
4. Termination

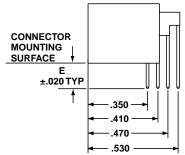
	Туре	Stickout (Dim. E)
01	PCB, Right Angle, .016 Dia.	0.090
02	PCB, Right Angle, .016 Dia.	0.120
03	PCB, Right Angle, .016 Dia.	0.150
04	PCB, Right Angle, .016 Dia.	0.180
06	PCB, Right Angle, .016 Dia.	0.300

5. Contact Termination Finish

2	Gold plated in accordance with MIL-G-45204, Type II, .00030 Min. thick Gold over .000050 Min. thick Nickel	
5	Tin plated in accordance with ASTM B545, .00010 Min. thick Matte Tin over .00010 Min. thick Nickel	
6	Tin-Lead plated in accordance with SAE-AMS-P-81728, .00010 Min. thick Tin-Lead over .00010 Min. thick Copper	







DAUGHTER BOARD LAYOUT

MATED HEIGHT DIMENSIONS DAUGHTER BOARD .060 DAUGHTER \emptyset .110 ±.005 BOARD CONNECTOR 000 ⊕ Ø.005 (M) 0 0 0 .025 0 0 MOTHER BOARD CONNECTOR .620 .560 .300 .500 .035 .070 BOARD .150 **EDGE** .205 FINISHED HOLE SIZE PER -CUSTOMER STANDARDS FOR MOTHER A Ø .016 PCB TAIL

HDB³ I/O CONNECTOR

FEATURES/BENEFITS

- For cable to cable
- Cable to board applications
- Crimp termination
- Uses wire well size 22D

HDB³ I/O – HOW TO ORDER

Mates with:
• Standard Mother Board

1. Connector Type

1.	2.	3.	4.
	Number of Contacts	Brush Wire Plating	Contact Termination Finish
HDB-D4C	120	C	2

Designates HDB³ I/0 Connector

2. Number of Contacts

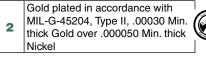
Number	Dimension	Dimension
of Contacts	Α	С
040	1.375	1.075
060	1.725	1.425
080	2.075	1.775
120	2.775	2.475
160	3.475	3.175

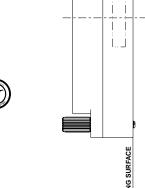
3. Brush Wire Plating

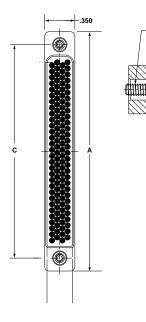
	0.000050 Au Min. thick over Nickel
C	0.000020 Au Min. thick over Nickel

4. Contact Termination Finish

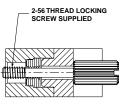
MATING MOTHER BOARD CONNECTOR







I/O Connector



Mother Board

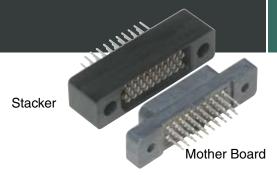
		MATIN		Contacts
0	ASSEMBLED INPUT/OUTPUT	¥		40
	CONNECTOR			60
				80
		FRONT HALF INPUT/OUTPUT		120
			EAR HALF	160
THREADED BOSS (2 REQUIRED FOR MOTHER BOARD CONNECTOR SEE HARDWARE ON PAGE 10)			EXPLOIS ISOME VIEW - 2 LOCKING SCREWS SUPPLIED	

REMOVABLE CRIMP CONTACTS -FOR SIZE 22 THRU 28 GAGE WIRE

HDB³ STACKER CONNECTOR

FEATURES/BENEFITS

• For applications that need or demand parallel boards



STACKER CONNECTOR - HOW TO ORDER

Mates with

Standard Mother Board

1.	2.	3.	4.	5.	
	Number of Contacts	Brush Wire Plating	Termination	Contact Termination Finish	Less Hardware (Purchased separately see pg 10 for hardware options)
HDB-D4S	120	C	21	2	X

1. Connector Type

HDB-D4S -

Designates HDB³ Stacker Connector.

2. Select the Number of Contacts

Number	Number of	Dimension	Dimension
Diff Signals	Contacts	Α	С
040	40	1.375	1.075
060	60	1.725	1.425
080	80	2.075	1.775
120	120	2.775	2.475
160	160	3.475	3.175

3. Select a Brush Wire Plating

M	0.000050 Au Min. thick over Nickel
C	0.000020 Au Min. thick over Nickel

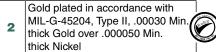
4. Select a Termination

	Туре	Stickout (Dim. E)
21	PCB, Straight, .016 Dia	0.090
22	PCB, Straight, .016 Dia	0.120
23	PCB, Straight, .016 Dia	0.150
24	PCB, Straight, .016 Dia	0.180
28	PCB, Straight, .016 Dia	0.300

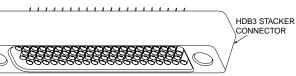
5. Contact Termination Finish

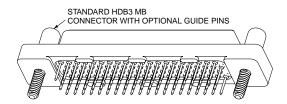
ISOMETRIC VIEW

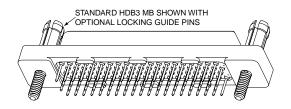
EXPLODED













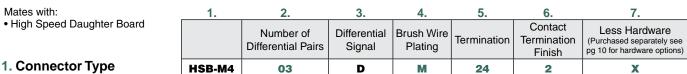
STICKOUT

HIGH SPEED BRUSH (HSB3) SERIES 3.125 Gb/s

BENEFITS

- High speed configuration available that allows data rates up to 3.125 Gb/s via 100 ohm matched impedance differential pairs
 - Partially populated standard HDB³ mother board & daughter board bodies
- Contact a Sales Engineer for validation results.

MOTHER BOARD - HOW TO ORDER



HSB-M4 -

Designates High Speed HSB3 Mother Board

2. Number of Contacts

Number Differential Pairs	No. Low Speed Signals	Dimension A	Dimension C
03	20	1.375	1.075
07	40	2.075	1.775
10	60	1.775	2.475
13	80	3.475	3.175

3. Differential Signal

D Standard

4. Brush Wire Plating

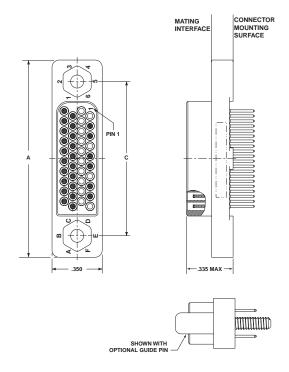
M	0.000050 Au Min. thick over Nickel
C	0.000020 Au Min. thick over Nickel

5. Termination

	Туре	Stickout (Dim. E)
22	PCB, Straight, .016 Dia	0.120
23	PCB, Straight, .016 Dia	0.150
24	PCB, Straight, .016 Dia	0.180
26	PCB, Straight, .016 Dia	0.240
28	PCB, Straight, .016 Dia	0.300

6. Contact Termination Finish

2	Gold plated in accordance with MIL-G-45204, Type II, .00030 Min. thick Gold over .000050 Min. thick Nickel	
5	Tin plated in accordance with ASTM B545, .00010 Min. thick Matte Tin over .00010 Min. thick Nickel	
6	Tin-Lead plated in accordance with SAE-AMS-P-81728, .00010 Min. thick Tin-Lead over .00010 Min. thick Copper	



STANDARI	D HDB ³ Connecte	or Dimensions
No. of Contacts	А	С
40	1.375	0.630
80	2.075	1.330
120	2.775	2.030
160	3.475	2.730

HIGH SPEED BRUSH (HSB3) SERIES 3.125 Gb/s

DAUGHTER BOARD - HOW TO ORDER

Mates with:

• High Speed Mother Board

	1.	2.	3.	4.	5.	6.	7.
		Number of Differential Pairs	Differential Signals	Brush Wire Plating	Termination	Contact Termination Finish	Less Hardware (Purchased separately see pg 10 for hardware options)
-	HSB-D4	03	D	M	02	2	X

1. Connector Type

HSB-D4

Designates High Speed HSB3 Daughter Board

2. Select a Number of Contacts

Number Diff Pairs	No. Low Speed Signals	Dimension A	Dimension C
03	20	1.375	1.075
07	40	2.075	1.775
10	60	2.775	2.475
13	80	3.475	3.175

3. Differential Signals

D	Star	ndai	•

4. Select a Brush Wire Plating

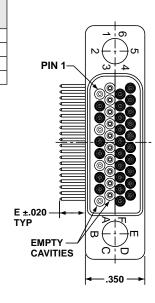
M	0.000050 Au Min. thick over Nickel
C	0.000020 Au Min, thick over Nickel

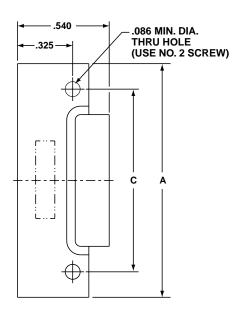
5. Select a Termination

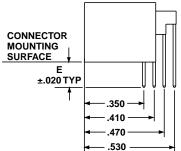
	Туре	Stickout (Dim. E)
01	PCB, Right Angle, .016 Dia	0.090
02	PCB, Right Angle, .016 Dia	0.120
03	PCB, Right Angle, .016 Dia	0.150
04	PCB, Right Angle, .016 Dia	0.180
06	PCB, Right Angle, .016 Dia	0.300

6. Select a Contact Termination Finish

		CHS
2	Gold plated in accordance with MIL-G-45204, Type II, .00030 Min. thick Gold over .000050 Min. thick Nickel	<i>(</i>)
5	Tin plated in accordance with ASTM B545, .00010 Min. thick Matte Tin over .00010 Min. thick Nickel	9
6	Tin-Lead plated in accordance with SAE-AMS-P-81728, .00010 Min. thick Tin-Lead over .00010 Min. thick Copper	







STANDARD HDB³ Connector Dimensions			
No. of Contacts	А	С	
40	1.375	0.630	
80	2.075	1.330	
120	2.775	2.030	
160	3.475	2.730	

HSB³ LAYOUT

	40 Pin Body	80 Pin Body	120 Pin Body	160 Pin Body
Differential Pairs	3	7	10	13
Low Speed Signal	20	40	60	80

As viewed from front of daughter board connector



= 100 Ohm Differential Pair (100 ohm differential contact pairs capable of 3.125 Gb/s data rates)

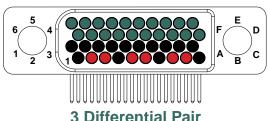


= Empty Contact Cavity



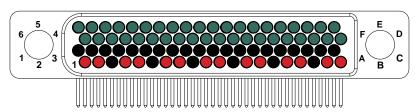
= Standard Digital, low speed signal contacts

HSB³ ARRANGEMENTS



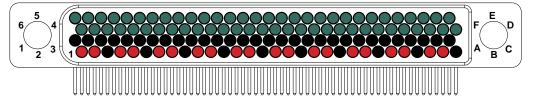
3 Differential Pair

(40 Pin Body)



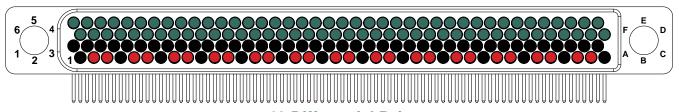
7 Differential Pair

(80 Pin Body)



10 Differential Pair

(120 Pin Body)



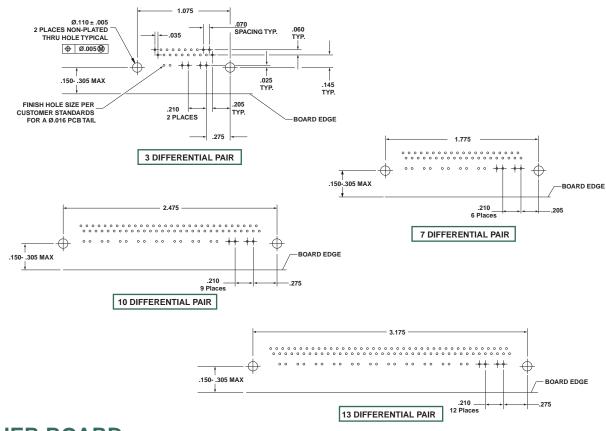
13 Differential Pair

(160 Pin body)

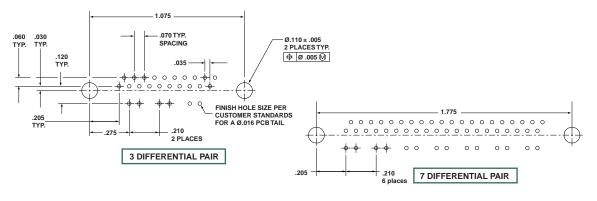
As viewed from front of daughter board connector

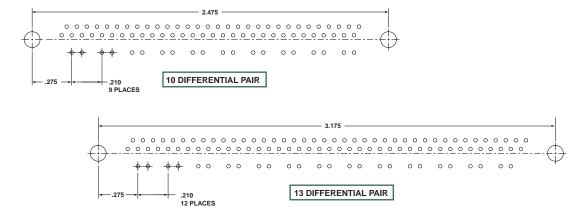
HSB³ RECOMMENDED BOARD LAYOUT

DAUGHTER BOARD



MOTHER BOARD





HARDWARE FOR HDB³ AND HSB³ CONNECTORS

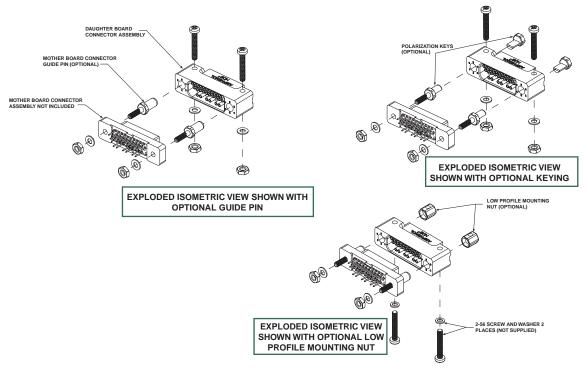
HARDWARE FOR ALL CONFIGURATIONS (Sold Separately)

MOTHER BOARD					
PART NUMBER	TYPE	STICKOUT			
HDB-508803-001	POLARIZATION KEY (QTY 2)	0.250			
HDB-508803-002	POLARIZATION KEY (QTY 2)	0.500			
HDB-508803-003	POLARIZATION KEY (QTY 2)	0.750			
HDB-508802-001	GUIDE PIN (QTY 2)	0.250			
HDB-508802-002	GUIDE PIN (QTY 2)	0.500			
HDB-508802-003	GUIDE PIN (QTY 2)	0.750			
HDB-508808-000	THREADED BOSS (QTY 2)*	0.250			
HDB-508808-001	THREADED BOSS (QTY 2)*	0.500			
HDB-508808-002	THREADED BOSS (QTY 2)*	0.750			
HDB-508808-020	LOCKING GUIDE PIN (QTY 2)	0.250			
HDB-508808-021	LOCKING GUIDE PIN (QTY 2)	0.500	Shown with		
HDB-508808-022	LOCKING GUIDE PIN (QTY 2)	0.750	Mother Board Connector on page 5		

 $^{^{\}star}$ Required with Mother Board only when mating to ${\rm I/O}$ Connector

	DAUGHTER BOARD			
PART NUMBER	TYPE	STICKOUT		
HDB-508804-000	POLARIZATION KEY (QTY 2)	0.200		
HDB-508804-001	LOW PROFILE MOUNTING NUT (QTY 2)	0.214		

EXPLODED ISOMETRIC VIEW





Amphenol Corporation Amphenol Aerospace 40-60 Delaware Avenue Sidney, New York 13838-1395

Phone: 800-678-0141

E-mail: blp-marketing@amphenol-aerospace.com

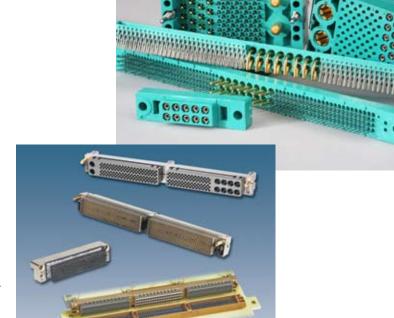
Web: www.amphenol-aerospace.com

MIL-DTL-55302 **BRUSH CONTACT** TECHNOLOGY - Catalog 12-035

Amphenol Bristle Brush Contact: Multiple Strands of High Tensile Strength Wires Bundled Together, Providing Superior Electrical Connection with Low Mating Force



Amphenol LRM Surface Mount Connectors meet the high density needs of today's integrated elctronic modules. Design versatility and product reliability makes Amphenol the premier choice for the system designer in solving board interconnect requirements.



NEW

MEDICAL CABLE CONNECTOR



- Utilize high performance B3 brush contact
- 10 contacts per connector
- Plug crimp removable contacts
- Receptacle printed circuit board contacts
- Currently available in 12 colors, each with a unique keying combination (plug only, user is to provide key hole for receptacle)
- Also offered as partially populated
- Notches in plug connector to assist with over molding

Notice: Specifications are subject to change without notice. Contact your nearest Amphenol Corporation Sales Office for the latest specifications. All statements, information and data given herein are believed to be accurate and reliable but are presented without guarantee, warranty, or responsibility of any kind, expressed or implied. Statements or suggestions concerning possible use of our products are made without representation or warranty that any such use is free of patent infringement and are not recommendations to infringe any patent. The user should assume that all safety measures are indicated or that other measures may not be required. Specifications are typical and may not apply to all connectors.

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NOTES	
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